<table>
<thead>
<tr>
<th>Quantity</th>
<th>RefDes</th>
<th>Value</th>
<th>Description</th>
<th>Size</th>
<th>Part Number</th>
<th>MFR</th>
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<tr>
<td>0</td>
<td>C1</td>
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<td>Capacitor, Ceramic, 35V, X7R, 10%</td>
<td>1210</td>
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<tr>
<td>1</td>
<td>C2</td>
<td>4.7uF</td>
<td>Capacitor, Ceramic, 25V, X7R, 10%</td>
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<tr>
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<td>2</td>
<td>C8-9</td>
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<td>Capacitor, Ceramic, 50V, X7R, 10%</td>
<td>1206</td>
<td>C3216X7R1H475M</td>
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<td>Power Di5 SBR8U60P5</td>
<td>Diodes Inc</td>
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<td>5</td>
<td>J1-5</td>
<td>PEC02SAAN</td>
<td>Header, Male 2-pin, 100mil spacing</td>
<td>0.100 inch x 2</td>
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<td>Sullins</td>
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<td>2</td>
<td>J6-7</td>
<td>ED555/2DS</td>
<td>Terminal Block, 2-pin, 6-A, 3.5mm</td>
<td>0.27 x 0.25 inch</td>
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<tr>
<td>2</td>
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<td>4.7uH</td>
<td>Inductor, SMT, 2.7A, 52.2 milliohm</td>
<td>4.3x4.3mm</td>
<td>XFL4020-472ME</td>
<td>Coilcraft</td>
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<tr>
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<td>U1</td>
<td>TPS5534ORTE</td>
<td>IC, 5-A High Voltage Boost Converter</td>
<td>QFN-16</td>
<td>TPS5534ORTE</td>
<td>TI</td>
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<tr>
<td>1</td>
<td>--</td>
<td>PCB, 2.6 In x 1.5 In x 0.062 In</td>
<td></td>
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<td></td>
</tr>
</tbody>
</table>
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